QUALIFICATION PLAN SUMMARY

PCN #: DSNO-22PBDH859

February 12, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material forSST25VF016B-50-4I-S2AF-GYR-T, SST25VF016B-50-4I-S2AF-GYR, SST25VF016B-50-4C-S2AF-T, SST25VF016B-50-4I-S2AF-T, SST25VF016B-50-4I-S2AF and SST25VF016B-50-4C-S2AF catalog part numbers (CPN) available in 8L SOIJ (.208in) package.

Purpose: **CCB 8073 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material forSST25VF016B-50-4I-S2AF-GYR-T, SST25VF016B-50-4I-S2AF-GYR, SST25VF016B-50-4C-S2AF-T, SST25VF016B-50-4I-S2AF-T, SST25VF016B-50-4I-S2AF and SST25VF016B-50-4C-S2AF catalog part numbers (CPN) available in 8L SOIJ (.208in) package.**

CCB No.: **8073**

Misc.	Assembly site		MTAI
	BD Number		BD-004168-01
	MP Code (MPC)		T0001T4BXD50
	Part Number (CPN)		SST25VF016B-50-4I-S2AF-T
	MSL information		MSL-3
	Assembly Shipping Media (T/R, Tube/Tray)		Tube
	Base Quantity Multiple (BQM)		90
	Reliability Site		MTAI
Lead-Frame	Paddle size		140x160 mils.
	Material		A194
	DAP Surface Prep		NiPdAu
	Treatment		Roughening LF
	Process		Stamped
	Lead-lock		No
	Part Number		10100837
	Lead Plating		NiPdAu
Bond Wire	Material		CuPdAu
Die Attach	Backside Coat (If Applicable)	Material	8006NS
		Thickness	2 mils max.
		Conductive	Non-Conductive
MC	Part Number		G600V
PKG	Package Type		SOIJ
	Pin/Ball Count		8
	PKG width/size		0.208"

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5			30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0 fails after TC	5			30 bonds from a min. 5 devices.
Wire Sweep										Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5			
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C° and 85C°.	45	5	3	150	0	10	MTAI	MTAI	
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25° and 85C. MSL-3 @260C°	231	15	3	738	0	15	MTAI	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25C° and 85C°.	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp (85C°); 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.